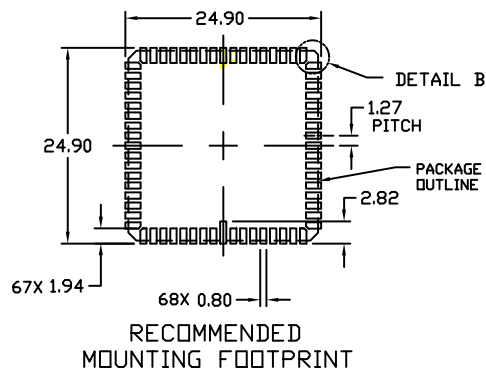
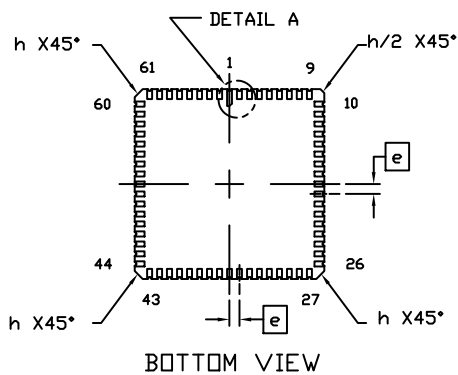
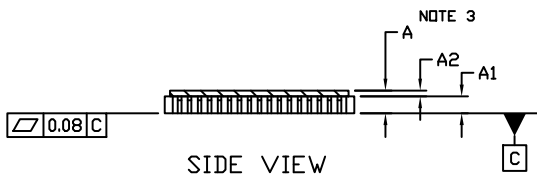
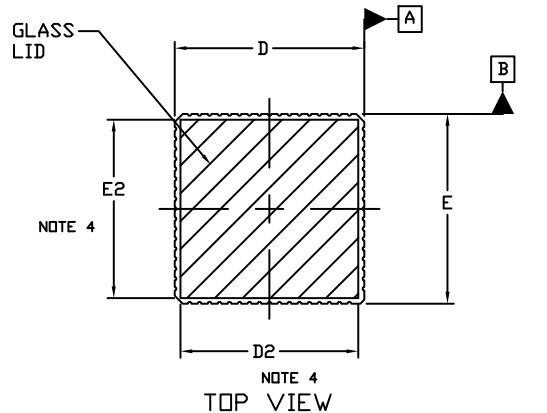


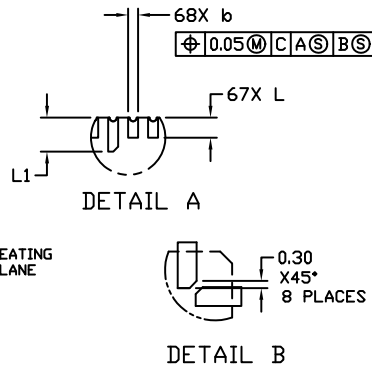
**LCC68, 24.13x24.13**  
**CASE 115AR**  
**ISSUE O**

DATE 30 JUN 2011



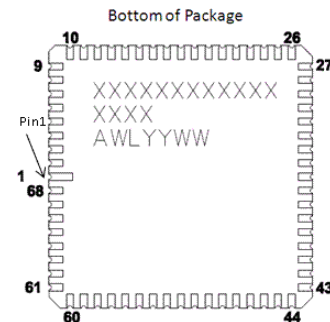
**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.



DIM	MILLIMETERS	
	MIN.	MAX.
A	2.46	3.16
A1	2.16	REF
A2	0.55	REF
b	0.50	0.77
D	23.88	24.51
D1	20.32	BSC
D2	23.50	REF
E	23.88	24.51
E2	23.50	REF
e	1.27	BSC
h	1.02	REF
L	1.07	1.47
L1	1.91	2.41

**GENERIC MARKING DIAGRAM**



XXXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week

<b>DOCUMENT NUMBER:</b>	<b>98AON56541E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>LCC68, 24.13 X 24.13</b>	<b>PAGE 1 OF 1</b>

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.